

### 30V P-Channel Enhancement Mode MOSFET

Voltage

-30 V

Current

-20 A

#### **Features**

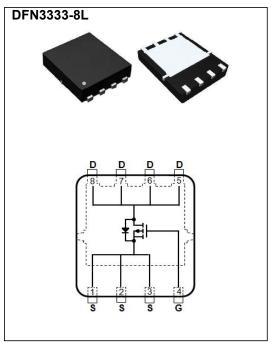
- $R_{DS(ON)}$ ,  $V_{GS}$ @-10V,  $I_{D}$ @-10A<12m $\Omega$
- $R_{DS(ON)}$ ,  $V_{GS}$ @-4.5V,  $I_{D}$ @-8A<18m $\Omega$
- Advanced Trench Process Technology
- High density cell design for ultralow on-resistance

#### Mechanical Data

• Case: DFN3333-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.001 ounces, 0.03 grams



### Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25 C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS
Drain-Source Voltage		V <sub>DS</sub>	-30	
Gate-Source Voltage		V <sub>GS</sub>	<u>+</u> 20	V
Continuous Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	-20	
Pulsed Drain Current (Note 1)	T <sub>C</sub> =25°C	I <sub>DM</sub>	-80	A
Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	59.5	W

Power Dissipation	T <sub>A</sub> =25°C	P <sub>D</sub>	2.1	W
Operating Junction and Storage Temperature Range		$T_{J}, T_{STG}$	-55~150	°C
Typical Thermal Resistance (Note 4,5)	Junction to Case	$R_{ heta JC}$	2.1	°0000
	Junction to Ambient		59.5	°C/W

• Limited only By Maximum Junction Temperature



# Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30	-	-	V	
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-1	-1.52	-2.5	V	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	-	10	12	mΩ	
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	-	13.5	18		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	-	-	-1.0	uA	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = <u>+</u> 20V, V <sub>DS</sub> =0V	-	-	<u>+</u> 100	nA	
Dynamic (Note 6)							
Total Gate Charge	Qg	\/ - 20\/ I - 40A	-	23	-	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ =-30V, $I_{D}$ =-10A, $V_{GS}$ =-4.5V (Note 1,2)	-	8.5	-		
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> 4.5 V	-	9	-		
Input Capacitance	Ciss	\	-	2767	-	pF	
Output Capacitance	Coss	V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V, f=1.0MHZ	-	247	-		
Reverse Transfer Capacitance	Crss	I-1.UIVINZ	-	139	-		
Turn-On Delay Time	td <sub>(on)</sub>	\/ - 00\/ I - 4A	-	23	-		
Turn-On Rise Time	t <sub>r</sub>	V <sub>DS</sub> =-20V, I <sub>D</sub> =-1A,	-	10	-		
Turn-Off Delay Time	td <sub>(off)</sub>	$V_{GS}$ =-10V, $R_G$ =6 $\Omega$	-	135	-	ns	
Turn-Off Fall Time	t <sub>f</sub>		-	50	-		
Drain-Source Diode							
Maximum Continuous Drain-Source	ا	Is			-46	A	
Diode Forward Current	IS		-	-	-40	_ ^	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V	-	-0.7	-1	V	

#### NOTES:

- 1. Pulse width < 300 us, Duty cycle < 2%
- 2. Essentially independent of operating temperature typical characteristics
- 3. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub> =25°C.
- 4. The maximum current rating is package limited
- 5. R<sub>OJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper
- 6. Guaranteed by design, not subject to production testing.



#### TYPICAL CHARACTERISTIC CURVES

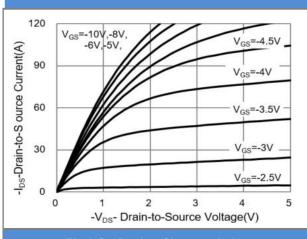
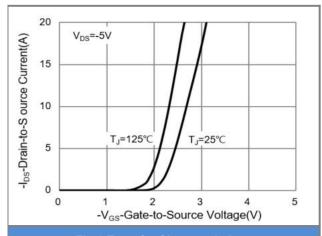


Fig.1 On-Region Characteristics



**Fig.2 Transfer Characteristics** 

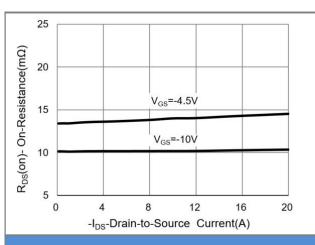


Fig.3 On-Resistance vs. Drain Current

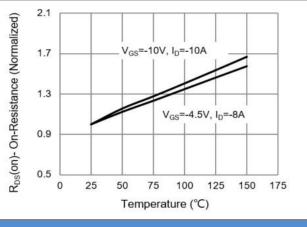


Fig.4 On-Resistance vs. Junction temperature

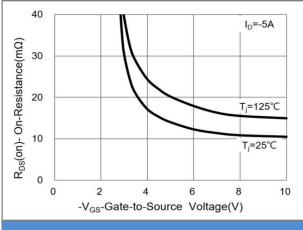


Fig.5 On-Resistance Variation with V<sub>GS</sub>

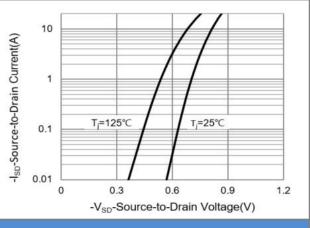


Fig.6 Source-Drain Diode Forward Voltage



#### TYPICAL CHARACTERISTIC CURVES

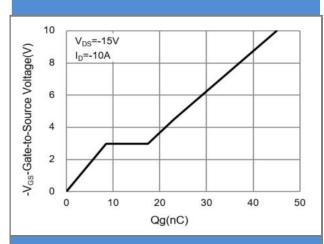


Fig.7 Gate-Charge Characteristics

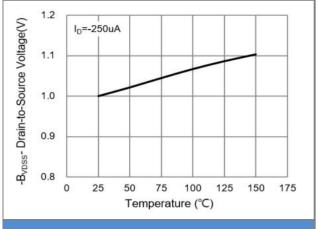


Fig.8 Breakdown Voltage Variation vs. Temperature

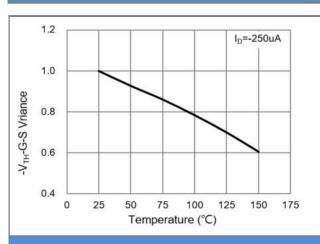


Fig.9 Threshold Voltage Variation with Temperature

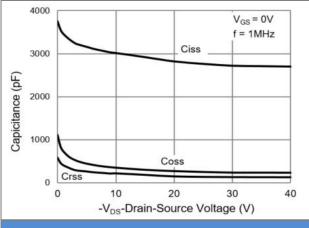
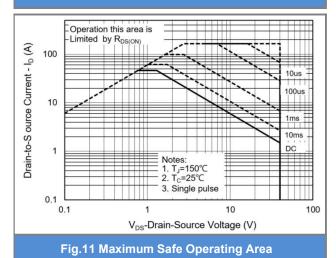


Fig.10 Capacitance vs. Drain-Source Voltage



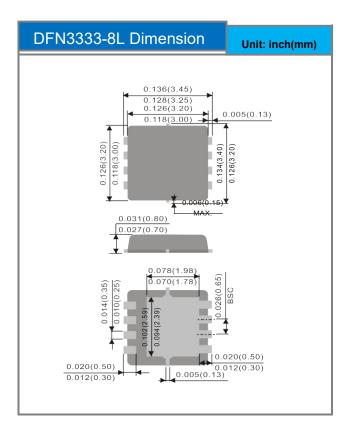
**Fig.12 Normalized Transient Thermal Impedance** 

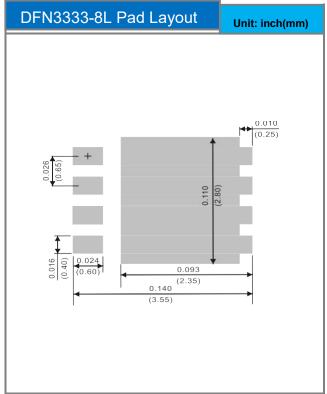


### **Part No Packing Code Version**

Part No Packing Code	Package Type	Packing Type
CSM320P20D3-3	DFN3333-8L	5K pcs / 13" reel

### **Packaging Information & Mounting Pad Layout**







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